1. Record Nr. UNISA996336700803316

Titolo	Hepatitis B annual / / Kalinga Gastroenterology Foundation
Pubbl/distr/stampa	Mumbai, India, : Wolters Kluwer - Medknow, [2004]-
ISSN	1998-3573
Descrizione fisica	1 online resource
Soggetti	Hepatitis B virus Hepatitis B Periodical Periodicals.
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Periodico
Note generali	Refereed/Peer-reviewed

2. Record Nr. UNINA9910830908503321

Autore	Li Er-Ping
Titolo	Electrical modeling and design for 3D system integration : 3D integrated circuits and packaging, signal integrity, power integrity and EMC / / Er-Ping Li
Pubbl/distr/stampa	[United States] : , : IEEE Press Hoboken [New Jersey] : , : Wiley [Piscataqay, New Jersey] : , : IEEE Xplore, , [2012]
ISBN	1-280-67311-7 9786613650047 1-118-16674-4 1-118-16672-8 1-118-16675-2
Descrizione fisica	1 online resource (390 p.)
Classificazione	TEC008050
Disciplina	621.3015118
Soggetti	Three-dimensional integrated circuits Integrated circuits
Lingua di pubblicazione	Inglese

Formato	Materiale a stampa
Livello bibliografico	Monografia
Note generali	Description based upon print version of record.
Nota di bibliografia	Includes bibliographical references and index.
Nota di contenuto	Macromodeling of Complex Interconnects in 3D Integration -- 2.5D Simulation Method for 3D Integrated Systems -- Hybrid Integral Equation Modeling Methods for 3D Integration -- Systematic Microwave Network Analysis for 3D Integrated Systems -- Modeling of Through-Silicon Vias (TSV) in 3D Integration.
Sommario/riassunto	New advanced modeling methods for simulating the electromagnetic properties of complex three-dimensional electronic systems Based on the author's extensive research, this book sets forth tested and proven electromagnetic modeling and simulation methods for analyzing signal and power integrity as well as electromagnetic interference in large complex electronic interconnects, multilayered package structures, integrated circuits, and printed circuit boards. Readers will discover the state of the technology in electronic package integration and printed circuit board simulation and